

**Electronic Assemblies With High Capacity Heat Sinks and Methods of
Manufacture**

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Abstract of the Disclosure

An electronic assembly comprising one or more high performance integrated circuits includes at least one high capacity heat sink. The heat sink, which
10 comprises a number of fins projecting substantially radially from a core, is structured to capture air from a fan and to direct the air to optimize heat transfer from the heat sink. The heat sink fins can be formed in different shapes. In one embodiment, the fins are curved. In another embodiment, the fins are bent. In yet another embodiment, the fins are curved and bent. Methods of fabricating heat
15 sinks and electronic assemblies, as well as application of the heat sink to an electronic assembly and to an electronic system, are also described.

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